SiCE-2020

Silicon Carbide in Europe 2020

A joint international workshop of the EU projects Challenge, Reaction and WInSiC4AP

Catania (Italy), Museo Diocesano - May 4-6, 2020



CHALLENGE project has received funding from the EU's H2020 framework programme for research and innovation under grant agreement n. 720827 from 1/1/2017 to 31/12/2020.





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WInSiC4AP project has received funding from the Electronic Component Systems for European Leadership Joint Undertaking (ECSEL JU) under grant agreement No.737483. The JU receives support from the European Union's Horizon 2020 research and innovation programme and Czech Republic, France, Germany, Italy. This project also receives ESI funds from MIUR 2014-2020 FESR program.











Scope

The event will be a scientific forum bringing together leading specialists working in different areas of silicon carbide (SiC) technology, both from universities, research centers and industries.

The workshop will address advances in both basic research, as well as SiC devices and applications in the field of power electronics. In particular, the aim of the workshop is to debate the latest achievements in SiC wafers growth, devices processing and applications, and to analyze their impact on the goals of the industry towards the development and commercialization of devices, modules and production equipment for several applications (automotive, railways transportation, avionics, renewable energies, etc.).

The workshop is organized in the framework of three running European projects on SiC (Challenge, Reaction and WInSiC4AP). This unique feature will enable the interaction of different communities, working on complementary aspects of SiC technology, thus being an efficient driving force for the further development of SiC research in Europe.

Important Dates

09/12/2019

First announcement

20/01/2020

Call for abstracts

06/03/2020

Deadline for abstract submission

20/03/2020

Notification of acceptance

03/04/2020

Dealine for early registration

04-06/05/2020

International Workshop SiCE-2020

Topics

- Bulk and Epitaxial Growth of SiC materials
- Material Characterization
- Surfaces and Interfaces in SiC devices
- Fabrication Processing (contacts, implantation doping, gate oxides, etc.)
- Power Devices (Schottky Diodes, JBS, MOSFETs, etc.)
- Modelling and Reliability
- Packaging, Power Modules and Circuit Technology
- System Applications (electric vehicles, railway, avionic, energy conversion, etc.)

Organizing Committee

Salvatore Frisella (DTSMNS, Italy)
Antonio Imbruglia (STMicroelectronics, Italy)
Francesco La Via (CNR-IMM, Italy)
Leoluca Liggio (DTSMNS, Italy)
Angelo Messina (STMicroelectronics, Italy)
Susanna Reggiani (Univ. of Bologna - IUNET, Italy)
Fabrizio Roccaforte (CNR-IMM, Italy)
Laura Vivani (Moverim Consulting, Belgium)

Venue

The scientific sessions of SiCE-2020 will be held in the Pinacoteca of the Diocesan Museum in Catania



Scientific Committee

Daniel Alguier (University of Tours, France) Tomasz Bieniek (ITE, Poland) Michele Calabretta (STMicroelectronics, Italy) Danilo Crippa (LPE, Italy) Ludovic Devidal (Valeo, France) Marius Enachescu (UPB, Romania) Patrick Fiorenza (CNR-IMM, Italy) Martin Haug (Würth, Germany) Antonio Imbruglia (STMicroelectronics, Italy) Mike Jennings (University of Swansea, UK) Antonino La Magna (CNR-IMM, Italy) Francesco La Via (CNR-IMM, Italy) Gaudenzio Meneghesso (Univ. of Padua - IUNET, Italy) Angelo Messina (STMicroelectronics, Italy) **Jean-François Michaud** (University of Tours, France) Susanna Reggiani (Univ. of Bologna - IUNET, Italy) Fabrizio Roccaforte (CNR-IMM, Italy) Mario Saggio (STMicroelectronics, Italy) Vincenzo Vinciguerra (STMicroelectronics, Italy) **Peter Wellmann** (University of Erlangen, Germany) Marcin Zielienski (Novasic, France)

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